

ABSTRACT

The present invention provides to a substrate for a semiconductor device, in which electric characteristics to high-speed signals are enhanced by facilitating the mounting of a circuit component, such as a decoupling capacitor, fabricated separately from the substrate. The substrate (30) for a semiconductor device, on which the circuit component (50), such as a decoupling capacitor, can be mounted, is counterbored from the mounting surface side thereof, and a component mounting hole (32) where a connection terminal (23a), which will be electrically connected to the circuit component (50), is exposed in the inner bottom face is made by counterboring. The circuit component (50) is mounted and electrically connected to the connection terminal (23a), and a semiconductor element (10) is mounted on the substrate by flip-chip connection.